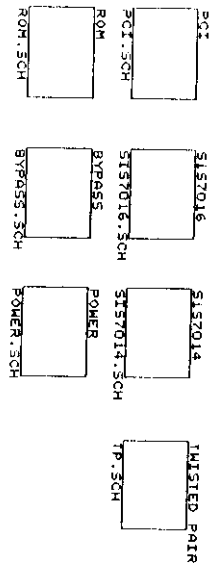


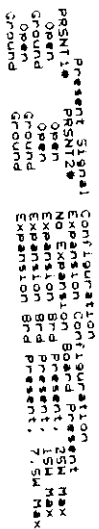
CIRCUIT DIAGRAM

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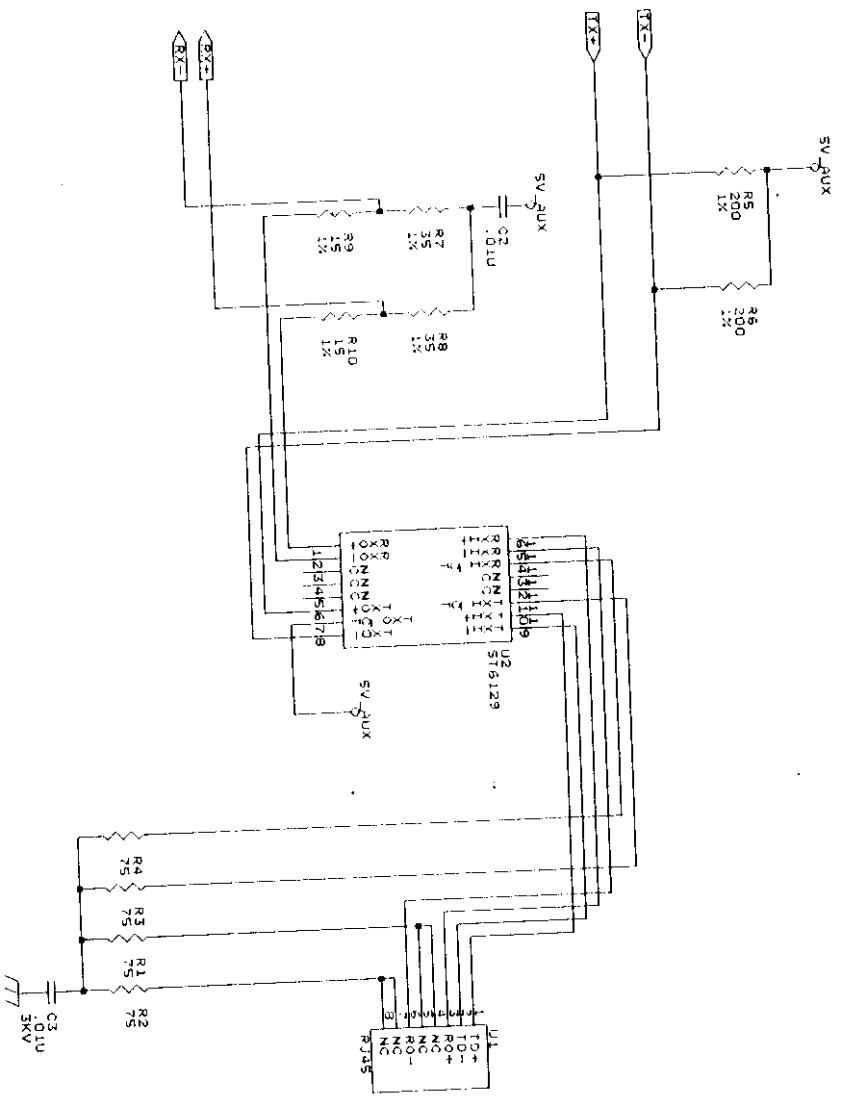


NOTE:
SIS IS NOT RESPONSIBLE FOR
ANY ERRORS OR OMISSIONS IN
THESE SCHEMATICS. THIS IS
AN EXAMPLE ONLY.

SILICON INTEGRATED SYSTEMS CORP.	
TITLE: SIS FAST ETHERNET DEMO CARD	
SIS Document Number	
REV	1.0
Date: February 3, 1993	
Page: 3	



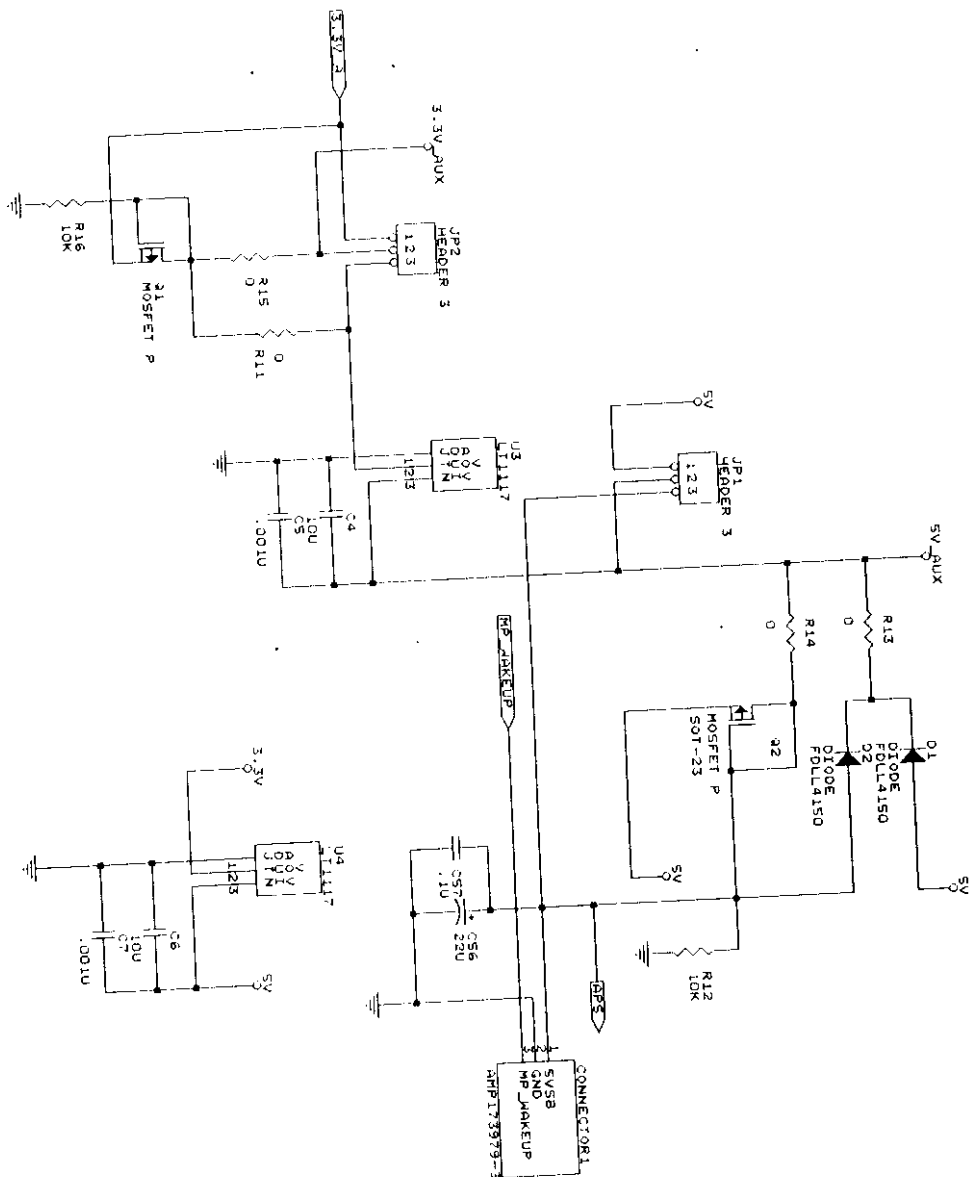
SILICON INTEGRATED SYSTEMS CORP.	
Item	REV
PCI SLOT	
Size/Document Number	1.0
6	
Date: February 3, 1998	Print 3 of 3



NOTE: THE METAL SHIELD OF THE CONNECTOR SHOULD BE TIED TO THE CHASSIS GROUND

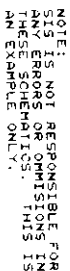
NOTE: NOT RESPONSIBLE FOR SIS LINE OR OMISSIONS IN THESE SCHEMATICS. THIS IS AN EXAMPLE ONLY.

SILICON INTEGRATED SYSTEMS CORP.		
Title	TWISTED PAIR	
Size	Document Number	REV
9		1.0
Date	FEBRUARY 2, 1988	Sheet 3 of 3

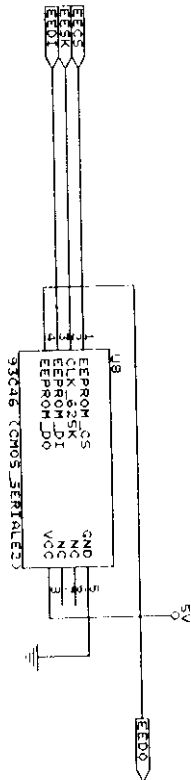
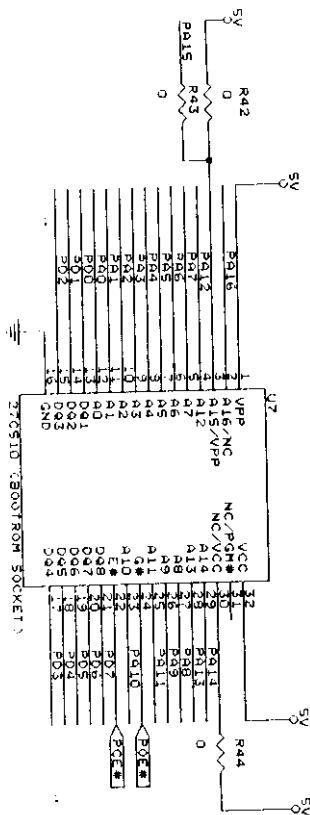


TITLE		POWER SUPPLY	
SHEET		1 OF 3	
DATE		FEBRUARY 2, 1993	
BY		J. STET	
REV		1.0	

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Silicon Integrated Systems Corp.	
Title	ROM (BootROM and EPROM)
Size/Document Number	REV 1.0
Date	February 3, 1993
Page	7 of 3



Notes: 1. All resistors are specified in Ohms and are

2. All capacitors are +80/-20% tolerance and 50V unless otherwise specified.

SILICON INTEGRATED SYSTEMS CORP.	
Title	BYPASS
Size	Document Number
B	REV 1.0